IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005. SINDUSTRIES international and P	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information			
upplier	r Information													
Company name* Company unique ID				ique ID	ue ID Unique I		nique ID Authority			Respo	Response Date*			
nsemi											2024-06-05			
ontact N	ame		Title - Conta	Title - Contact			Phone - Contact*			Email	Email - Contact*			
Product-F	Env-Stewards		Product Enviro Compliance			1	NA			Prod	Product-Env-Stewards@onsemi.com			
uthorize	d Representative*	Title - Repre	Title - Representative			Phone - Representative*			Email	Email - Representative*				
roduct-I	Env-Stewards	Product Env	Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr		tem Number Mfr Item Name				Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
		J112 NFET/S TO-92		NFET/S TO-92			2024-06-05 CNF			219.001	mg	Each		
lanufa	cturing Process Informa		Terminal Base	Alloy	I-STD-020 MS	I. Poting	Pagir Progra	os Pody Tompor	sture May Time o	t Dook Tompo	ratura Numb	or of Poflow Cv	olos	
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RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.075	mg	Supplier	Silicon (Si)	7440-21-3		0.075	mg
Lead Frame	101.0	mg	Supplier	Silver (Ag)	7440-22-4		0.0101	mg
			Supplier	Iron (Fe)	7439-89-6		0.101	mg
			Supplier	Copper (Cu)	7440-50-8		100.8586	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0303	mg
Mold Compound-Black	112.0			Phenol Resin	proprietary data		11.2	mg
			Supplier	Carbon Black (C)	1333-86-4		1.12	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		86.24	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		13.44	mg
Plating	5.85	mg	Supplier	Tin (Sn)	7440-31-5		5.85	mg
Wire Bond - Au	0.076	mg	Supplier	Gold (Au)	7440-57-5		0.076	mg